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## 1 Description

The iW1830 is a high performance AC/DC power supply control device that uses digital control technology to build peak current mode PWM flyback power supplies. The device includes an internal power MOSFET and operates in quasi-resonant mode and includes key built-in protection features. This combination of features and integration simplifies design, improves efficiency, reduces EMI and lowers the bill of material cost.

The iW1830 removes the need for a secondary feedback circuit while achieving excellent line and load regulation. It also eliminates the need for loop compensation components while maintaining stability over all operating conditions. The pulse-by-pulse waveform analysis allows for a loop response that is much faster than traditional solutions, resulting in improved dynamic load response. The built-in power limit function enables optimized transformer design in universal off-line applications and allows for a wide input voltage range.

Dialog's innovative proprietary technology ensures that power supplies built with the iW1830 can achieve both the highest average efficiency and less than 50mW no-load power consumption in the 15W output power range, and have

## 2 Features

- PrimAccurate<sup>™</sup> primary-side feedback eliminates opto-isolators and simplifies design
- Integrated 700V power MOSFET
- Tight constant-voltage regulation across line and load range
- Proprietary optimized 79kHz maximum PWM switching frequency with quasi-resonant operation achieves best size, efficiency and common mode noise
- No-load power consumption < 50mW at 230V<sub>AC</sub> along with fast dynamic load response and short turn-on delay in typical 15W adapter applications

## 3 Applications

- Home appliances
- Power adapters for network devices and monitors
- Universal input AC/DC adapters (up to 15W)

- Adaptively controlled soft-start enables fast and smooth start-up for a wide range of capacitive loads (from 330μF to 6,000μF) with output voltage of 12V and above
- EZ-EMI® design enhances manufacturability
- Adaptive multi-mode PWM/PFM control improves efficiency
- Built-in single-point fault protections against output short-circuit, output over-voltage and output overcurrent
- Built-in over-temperature protection (OTP)
- No audible noise over entire operating range





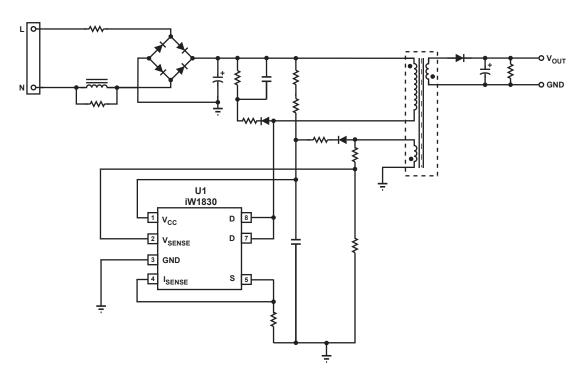


Figure 3.1: iW1830 Typical Application Circuit

## **WARNING:**

The iW1830 is intended for high voltage AC/DC offline applications. Contact with live high voltage offline circuits or improper use of components may cause lethal or life threatening injuries or property damage. Only qualified professionals with safety training and proper precaution should operate with high voltage offline circuits.

## iW1830 Output Power Table at Universal Input (85V<sub>AC</sub>-264V<sub>AC</sub>)

Condition	Open Frame <sup>1</sup>	
Output Power (W) <sup>2</sup>	15.0	

#### Notes:

- Note 1. Maximum practical continuous output power measured at open frame ambient temperture of 50°C and device package/ pin temperatures of ≤ 100°C while minimum bulk capacitor voltage is kept above 90V and no special heatsinking is used (test unit is placed in a non-ventilated environment).
- Note 1. The output power can vary depending on the power supply system designs and operating conditions.



## **4 Pinout Description**

# 

Figure 4.1: 7-Lead PDIP Package

Pin Number	Pin Name	Туре	Pin Description
1	$V_{CC}$	Power Input	IC power supply.
2	$V_{SENSE}$	Analog Input	Auxiliary voltage sense. Used for primary side regulation.
3	GND	Ground	Ground.
4	I <sub>SENSE</sub>	Analog Input	Primary current sense. Used for cycle-by-cycle peak current control and limit.
5	S	MOSFET Source	Source of the internal power MOSFET (pin 4 and pin 5 must be shorted externally on the PCB).
7	D	MOSFET Drain	Drain of the internal power MOSFET.
8	D	MOSFET Drain	Drain of the internal power MOSFET.



## 5 Absolute Maximum Ratings

Absolute maximum ratings are the parameter values or ranges which can cause permanent damage if exceeded.

Parameter	Symbol	Value	Units
DC supply voltage range (pin 1, I <sub>CC</sub> = 20mA max)	V <sub>CC</sub>	-0.3 to 25.0	V
Continuous DC supply current at V <sub>CC</sub> pin (V <sub>CC</sub> = 15V)	I <sub>cc</sub>	20	mA
V <sub>SENSE</sub> input (pin 2, I <sub>Vsense</sub> ≤ 10mA)		-0.7 to 4.0	V
I <sub>SENSE</sub> input (pin 4)		-0.3 to 4.0	V
Drain-source voltage	V <sub>DSS</sub>	700	V
Continuous drain current @ T <sub>C</sub> =25°C		4	А
Continuous drain current @ T <sub>C</sub> =100°C	l <sub>D</sub>	2.9	
Pulsed drain current (Note 1)	I <sub>DM</sub>	16	А
Single Pulse Avalanche Energy (starting T <sub>J</sub> = 25°C)	E <sub>AS</sub>	150	mJ
Maximum junction temperature	T <sub>JMAX</sub>	150	°C
Operating junction temperature	T <sub>JOPT</sub>	-40 to 150	°C
Storage temperature	T <sub>STG</sub>	-55 to 150	°C
Electrostatic Discharge Capability (Human Body Model), JEDEC JS-001-2012	ESD <sub>(HBM)</sub>	±4.5	kV
Electrostatic Discharge Capability (Charge Device Model), JEDEC JESD22-C101	ESD <sub>(CDM)</sub>	±1.0	kV
Latch-up test per JESD78A		±100	mA

### Notes:

Note 1. Repetitive rating; pulse width limited by maximum junction temperature.

## **6 Thermal Characteristics**

Parameter	Symbol	Value	Units
Thermal Resistance Junction-to-Ambient <sup>1</sup>	$\theta_{JA}$	80	°C/W
Thermal Resistance Junction-to-GND pin (pin 3) <sup>2</sup>	ΨЈВ	25	°C/W
Thermal Resistance Junction-to-Drain pin (pin 7 and pin 8) <sup>2</sup>	Ψ <sub>J-MOSFET</sub>	35	°C/W
Thermal Shutdown Threshold <sup>3</sup>	T <sub>SD</sub>	150	°C
Thermal Shutdown Recovery <sup>3</sup>	T <sub>SD-R</sub>	120	°C

### Notes:

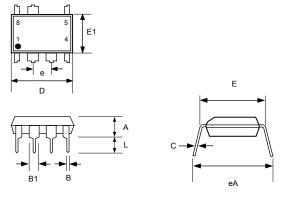
- Note 1. Device is mounted on a JEDEC single-sided board with  $100 \text{mm}^2$  of  $35 \mu \text{m}$  thick copper, in a one-cubic-foot natural convection chamber with 1W dissipated power.
- Note 2.  $\psi_{JB}$  [Psi Junction to Board] provides an estimation of the die junction temperature relative to the PCB [Board] surface temperature.  $\psi_{J-MOSFET}$  [Psi Junction to Drain pin] provides an estimation of the die junction temperature relative to the Drain pin [internal MOSFET Drain] surface temperature.  $\psi_{JB}$  is measured at the ground pin (pin 3) without using any thermal adhesives. See Section 10.14 for more information.
- Note 3. These parameters are typical and they are guaranteed by design.

Product Summary Rev. 1.0 23-August-2016



## 7 Physical Dimensions

## 7-Lead Plastic Dual In-Line (PDIP) Package



Symbol	Inc	hes	Millimeters		
Syr	MIN	MAX	MIN	MAX	
Α	0.135	0.145	3.429	3.683	
В	0.015	0.021	0.381	0.533	
B1	0.050	0.065	1.270	1.650	
С	0.007	0.014	0.200	0.356	
D	0.367	0.387	9.322	9.830	
Е	0.300	0.325	7.620	8.255	
E1	0.240	0.260	6.096	6.604	
е	0.1 E	SC	2.54 BSC		
eА	0.332	0.392	8.433	9.957	
L	0.120	0.140	3.048	3.556	

Compliant to JEDEC Standard MS12F

Controlling dimensions are in inches; millimeter dimensions are for reference only

This product is RoHS compliant and Halide free.

Soldering Temperature Resistance:

- [a] Package is IPC/JEDEC Std 020D Moisture Sensitivity Level 1
- [b] Package exceeds JEDEC Std No. 22-A111 for Solder Immersion Resistance; package can withstand 10 s immersion < 260°C</p>

Dimension D does not include mold flash, protrusions or gate burrs. Mold flash, protrusions or gate burrs shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion. Interlead flash or protrusion shall not exceed 0.25 mm per side.

The package top may be smaller than the package bottom. Dimensions D and E1 are determined at the outermost extremes of the plastic bocy exclusive of mold flash, tie bar burrs, gate burrs and interlead flash, but including any mismatch between the top and bottom of the plastic body.

## **8 Ordering Information**

Part no.	Options	Package	Description
iW1830-00	No CC operation, no latch	PDIP-7	Tube <sup>1</sup>
iW1830-01	OVP/OTP latch, no CC operation with latch	PDIP-7	Tube <sup>1</sup>

Note 1: Packing quantity is 50 units/tube, 1,000 units (20 tubes)/box. Minimum ordering quantity is 1,000 units.



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Dialog Semiconductor complies to European Directive 2001/95/EC and from 2 January 2013 onwards to European Directive 2011/65/EU concerning Restriction of Hazardous Substances (RoHS/RoHS2).

Dialog Semiconductor's statement on RoHS can be found on the customer portal https://support.diasemi.com/. RoHS certificates from our suppliers are available on request.

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Product Summary Rev. 1.0 23-August-2016